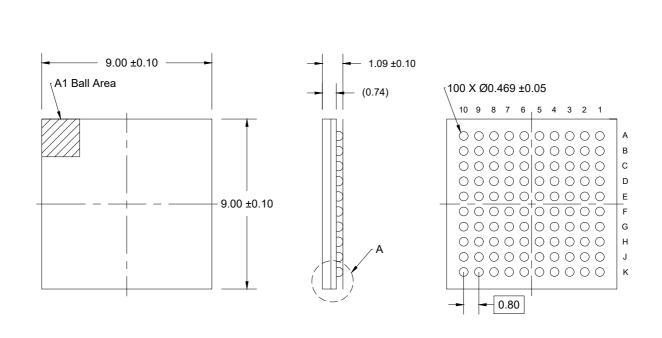


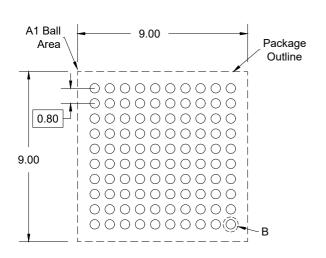


Package Code: BJG100 100-BGA 9.00 x 9.00 x 1.09 mm Body, 0.80 mm Pitch

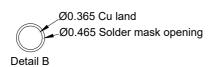
PSC-4959-01, Revision: 01, Date Created: Mar 14, 2023

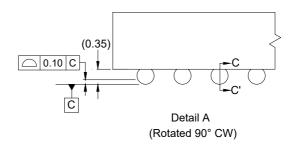


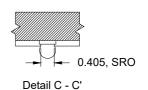
TOP VIEW SIDE VIEW BOTTOM VIEW



## RECOMMENDED LAND PATTERN (PCB Top View, NSMD Design)







## NOTES:

- 1. JEDEC compatible.
- 2. All dimensions are in mm and angles are in degrees.
- 3. Use ±0.05 mm for the non-toleranced dimensions.
- 4. Numbers in ( ) are for references only.
- 5. Pre-reflow solderball diameter is Ø0.45 mm.